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SEMICONDUCTOR DEVICE

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[There are no amendments to this patent.]

Claims

1. Semiconductor device characterized in that,
bump (2), made of indium (In) or an alloy that contains
indium, formed on first semiconductor chip (1),
with alloy-forming metal layer (3), forming an alloy with
indium at a temperature lower than the melting point of indium,
between them,
being made to contact bump (5) on second semiconductor chip
(4) and with the two semiconductor chips (1) and (4) being
bonded.
2. The semiconductor device described in Claim 1, wherein
either of the aforementioned semiconductor chips (1) or (4) is
made from mercury-cadmium-tellurium (HgCdTe) crystals.
3. The semiconductor device described in Claim 1, wherein
aforementioned alloy-forming metal layer (3) is made from gold
(Au).

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